<u>"PCBqoqo</u>

PCBGOGO Multi-layer PCB Standard Stackup

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
771101111000	copper unon (cutominor)	A	L1	Copper 18 umplating to 35um
				PP 0.08 mm dielectric constant 4.29
		00000	L2	
0.4mm±0.1mm	1/1oz	00000		Core 0.2mm with 1/1 oz Cu
			L3	
		0000		PP 0.08 mm dielectric constant 4.29
			L4	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
			L2	
0.6mm±0.1mm	1/1oz			Core 0.2mm with 1/1 oz Cu
			L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 18 umplating to 35um
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
			L2	
0.6mm±0.1mm	1/1oz			Core 0.3mm with 1/1 oz Cu
			L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.11 mm dielectric constant 4.29
			L2	
0.6mm±0.1mm	2/1oz			Core 0.2mm with 1/1 oz Cu
		4444	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		00000	L2	
0.8mm±0.1mm	1/1oz			Core 0.4mm with 1/1 oz Cu
		11111	L3	
				PP 0.11 mm dielectric constant 4.29
		11111	L4	Copper 18 umplating to 35um
		11111		Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um
		11111	L4 L1	Copper 18 umplating to 35um
0.000010.4000		11111	L4	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29
0.8mm±0.1mm	2/1oz	11111	L4 L1	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um
0.8mm±0.1mm		11111	L4 L1	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu
0.8mm±0.1mm		11111	L4 L1 L2	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29
0.8mm±0.1mm		11111	L4 L1 L2 L3	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um
0.8mm±0.1mm		11111	L4 L1 L2	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um
0.8mm±0.1mm		11111	L4 L1 L2 L3 L4 L1	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um
	2/1oz	11111	L4 L1 L2 L3	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29
		11111	L4 L1 L2 L3 L4 L1 L4 L1 L2 L2	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um
	2/1oz	11111	L4 L1 L2 L3 L4 L1	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29 Core 0.3mm with 1/1 oz Cu
	2/1oz	11111	L4 L1 L2 L3 L4 L1 L2	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29 Core 0.3mm with 1/1 oz Cu
	2/1oz	11111	L4 L1 L2 L3 L4 L1 L2 L3	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29 Core 0.3mm with 1/1 oz Cu PP 0.18 mm dielectric constant 4.29 Copper 18 umplating to 35um
	2/1oz	11111	L4 L1 L2 L3 L4 L1 L2	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29 Core 0.3mm with 1/1 oz Cu PP 0.18 mm dielectric constant 4.29 Copper 18 umplating to 35um Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um
	2/1oz	11111	L4 L1 L2 L3 L4 L1 L2 L3 L4 L1 L2 L3 L4 L1 L1 L2 L3	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29 Core 0.3mm with 1/1 oz Cu PP 0.18 mm dielectric constant 4.29 Copper 18 umplating to 35um
0.8mm±0.1mm	2/1oz 1/1oz	11111	L4 L1 L2 L3 L4 L1 L2 L3	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29 Core 0.3mm with 1/1 oz Cu PP 0.18 mm dielectric constant 4.29 Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.22 mm dielectric constant 4.29
0.8mm±0.1mm 0.8mm±0.1mm	2/1oz	11111	L4 L1 L2 L3 L4 L1 L2 L3 L4 L1 L2 L3 L4 L1 L2 L3 L4 L1 L2	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29 Core 0.3mm with 1/1 oz Cu PP 0.18 mm dielectric constant 4.29 Copper 18 umplating to 35um Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um
0.8mm±0.1mm	2/1oz 1/1oz	11111	L4 L1 L2 L3 L4 L1 L2 L3 L4 L1 L2 L3 L4 L1 L1 L2 L3	Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.4mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 18 umplating to 35um PP 0.18 mm dielectric constant 4.29 Core 0.3mm with 1/1 oz Cu PP 0.18 mm dielectric constant 4.29 Copper 18 umplating to 35um Copper 50um(±5)um-plating to 70um PP 0.22 mm dielectric constant 4.29

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		0000	L2	
1.0mm±0.1mm	1/1oz	00000		Core 0.6mm with 1/1 oz Cu
			L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.11 mm dielectric constant 4.29
		0000	L2	
1.0mm±0.1mm	2/1oz			Core 0.6mm with 1/1 oz Cu
			L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.22 mm dielectric constant 4.29
		0000	L2	
1.0mm±0.1mm	2/1.5oz			Core 0.4mm with 1.5/1.5 oz Cu
			L3	
				PP 0.22 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
			= -	Copper Souri(±S)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
Thickness	Copper thick (outer/inner)	StackUp		
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness Copper 18 um-plating to 35um
Thickness 1.2mm±10%	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness Copper 18 um-plating to 35um
		StackUp	Layer No.	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29
		StackUp	Layer No. L1 L2	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29
		StackUp	Layer No. L1 L2 L3 L4	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu
		StackUp	Layer No. L1 L2 L3	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um
		StackUp	Layer No. L1 L2 L3 L4 L1	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um
1.2mm±10%	1/1oz		Layer No. L1 L2 L3 L4	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29
		StackUp	Layer No. L1 L2 L3 L4 L1 L2	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um
1.2mm±10%	1/1oz		Layer No. L1 L2 L3 L4 L1	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu
1.2mm±10%	1/1oz		Layer No. L1 L2 L3 L4 L1 L2 L3 L4 L1	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu
1.2mm±10%	1/1oz		Layer No. L1 L2 L3 L4 L1 L2 L3 L4 L4 L1 L2 L3	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um
1.2mm±10%	1/1oz		Layer No. L1 L2 L3 L4 L1 L2 L3 L4 L1	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu
1.2mm±10%	1/1oz		Layer No. L1 L2 L3 L4 L1 L2 L3 L4 L1 L1 L2 L3	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um
1.2mm±10%	1/1oz		Layer No. L1 L2 L3 L4 L1 L2 L3 L4 L4 L1 L2 L3	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um
1.2mm±10%	1/1oz		Layer No. L1 L2 L3 L4 L1 L2 L3 L4 L1 L1 L2 L3	Laminated chart Thickness Copper 18 um-plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um-plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um
1.2mm±10% 1.2mm±10%	1/1oz 2/1oz		Layer No. L1 L2 L3 L4 L1 L2 L3 L4 L1 L1 L2 L3	Laminated chart Thickness Copper 18 um—plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um—plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um PP 0.22 mm dielectric constant 4.29
1.2mm±10% 1.2mm±10%	1/1oz 2/1oz		Layer No. L1 L2 L3 L4 L1 L2 L3 L4 L1 L2 L3 L4 L1 L2 L4 L1 L2	Laminated chart Thickness Copper 18 um—plating to 35um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 18 um—plating to 35um Copper 50um(±5)um-plating to 70um PP 0.11 mm dielectric constant 4.29 Core 0.8mm with 1/1 oz Cu PP 0.11 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um PP 0.22 mm dielectric constant 4.29

Thickness	Conner thick (outer/inner)	Ctooki In	Laver No	Laminated short Thickness
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			LI	Copper 18 umplating to 35um
			L2	PP 0.11 mm dielectric constant 4.29
1.6mm±10%	1/1oz	00000	LZ	Core 1.2mm with 1/1 oz Cu
1.011111±10 /6	1/102	11111	L3	Core 1.2mm with 1/1 02 Cu
		0000	LJ	PP 0.11 mm dielectric constant 4.29
			L4	Copper 18 umplating to 35um
			L1	
			LT	Copper 50um(±5)um-plating to 70um
			10	PP 0.11 mm dielectric constant 4.29
1.0100/	044	11111	L2	0 40 9 7 44 9
1.6mm±10%	2/1oz	11111	10	Core 1.2mm with 1/1 oz Cu
		00000	L3	DD 0.44 I'. I . 1 . 1 . 1 . 1 . 1 . 1 . 1 . 1 . 1
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
			10	PP 0.22 mm dielectric constant 4.29
1.0100/	04.5	11111	L2	0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
1.6mm±10%	2/1.5oz	11111		Core 1mm with 1.5/1.5 oz Cu
		00000	L3	
				PP 0.22 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.18 mm dielectric constant 4.29
		11111	L2	
2.0mm±10%	1/1oz			Core 1.6mm with 1/1 oz Cu
		11111	L3	
				PP 0.18 mm dielectric constant 4.29
			L4	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.11 mm dielectric constant 4.29
		11111	L2	
2.0mm±10%	2/1oz			Core 1.6mm with 1/1 oz Cu
		11111	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.29 mm dielectric constant 4.29
		10000	L2	
2.0mm±10%	2/1.5oz			Core 1.2mm with 1.5/1.5 oz Cu
		11111	L3	
				PP 0.29 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.18 mm dielectric constant 4.29
			L2	
2.4mm±10%	1/1oz	00000		Core 2mm with 1/1 oz Cu
			L3	
				PP 0.18 mm dielectric constant 4.29
			L4	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.18 mm dielectric constant 4.29
		00000	L2	
2.4mm±10%	2/1oz	00000		Core 2mm with 1/1 oz Cu
		11111	L3	
		00000		PP 0.18 mm dielectric constant 4.29
			L4	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
			<u>- 1</u>	PP 0.36 mm dielectric constant 4.29
			L2	1 1 0.50 min dicieculo constalit 4.29
	2/1.5oz		LZ	Core 1 6mm with 1 5/1 5 oz Cu
0.4	7/1 507			Core 1.6mm with 1.5/1.5 oz Cu
2.4mm±10%	2/1.302	11 11 11 11 11	1.0	
2.4mm±10%	2/1.502	11111	L3	DD 0.00 and distant
2.4mm±10%	2/1.502	11111	L3	PP 0.36 mm dielectric constant 4.29 Copper 50um(±5)um-plating to 70um

Note: The above is the standard stackup of PCBGOGO's 4-layer PCB board, we may change the layer stackup according to latest material or technology. For more details The custom stackup is available, feel free to contact us via service@pcbgogo.com.

6-Layer PCB Boar	d			
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
		4		PP 0.11 mm dielectric constant 4.29
			L2	
		4444		Core 0.2mm with 1/1 oz Cu
			L3	
0.8mm ±0.1mm	1/1oz	4.000		PP 0.11 mm dielectric constant 4.29
±0.1111111			L4	
				Core 0.2mm with 1/1 oz Cu
			L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
		4		PP 0.18 mm dielectric constant 4.29
			L2	
		11111		Core 0.2mm with 1/1 oz Cu
		11111	L3	
1.0mm ±0.1mm	1/1oz			PP 0.18 mm dielectric constant 4.29
10.111111			L4	
				Core 0.2mm with 1/1 oz Cu
		0000	L5	
				PP 0.18 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.2mm with 1/1 oz Cu
4.0			L3	
1.0mm ±0.1mm	2/1oz	0.00.00		PP 0.22 mm dielectric constant 4.29
			L4	
				Core 0.2mm with 1/1 oz Cu
		0000	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		11111	L2	
		00000		Core 0.4mm with 1/1 oz Cu
		11111	L3	
1.2mm±10%	1/1oz			PP 0.11 mm dielectric constant 4.29
		11111	L4	
				Core 0.4mm with 1/1 oz Cu
			L5	
				PP 0.11 mm dielectric constant 4.29
1			L6	Copper 18 umplating to 35um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.18 mm dielectric constant 4.29
			L2	
		-		Core 0.2mm with 1/1 oz Cu
			L3	
1.2mm±10%	2/1oz			PP 0.18 mm dielectric constant 4.29
			L4	
				Core 0.2mm with 1/1 oz Cu
		00000	L5	
				PP 0.18 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.22 mm dielectric constant 4.29
			L2	
				Core 0.2mm with 1.5/1.5 oz Cu
		11111	L3	
1.2mm±10%	2/1.5oz			PP 0.22 mm dielectric constant 4.29
			L4	
				Core 0.2mm with 1.5/1.5 oz Cu
			L5	
				PP 0.22 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		0000	L2	
		11111		Core 0.6mm with 1/1 oz Cu
			L3	
1.6mm±10%	1/1oz	4444		PP 0.11 mm dielectric constant 4.29
			L4	
				Core 0.6mm with 1/1 oz Cu
			L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.18 mm dielectric constant 4.29
		0000	L2	
		00000		Core 0.4mm with 1/1 oz Cu
		11111	L3	
1.6mm±10%	2/1oz	00000		PP 0.18 mm dielectric constant 4.29
		11111	L4	
				Core 0.4mm with 1/1 oz Cu
			L5	
				PP 0.18 mm dielectric constant 4.29
I	1		L6	Copper 50um(±5)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
	, ,		L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.22 mm dielectric constant 4.29
		-	L2	
				Core 0.4mm with 1.5/1.5 oz Cu
			L3	
1.6mm±10%	2/1.5oz	0000		PP 0.22 mm dielectric constant 4.29
		00000	L4	
				Core 0.4mm with 1.5/1.5 oz Cu
		00000	L5	
				PP 0.22 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
		p	L1	Copper 18 umplating to 35um
		4		PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.8mm with 1/1 oz Cu
			L3	
2.0mm±10%	1/1oz	0.000		PP 0.11 mm dielectric constant 4.29
			L4	
		11111		Core 0.8mm with 1/1 oz Cu
		00000	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
	,		L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.8mm with 1/1 oz Cu
			L3	
2.0mm±10%	2/1oz			PP 0.11 mm dielectric constant 4.29
			L4	
				Core 0.8mm with 1/1 oz Cu
		0000	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.22 mm dielectric constant 4.29
			L2	
		11111		Core 0.6mm with 1.5/1.5 oz Cu
2.0mm+10%			L3	
	2/1 507			PP 0.22 mm dielectric constant 4.29
2.0mm±10%	2/1.5oz			
2.0mm±10%	2/1.5oz	00000	L4	
2.0mm±10%	2/1.5oz	11111	L4	Core 0.6mm with 1.5/1.5 oz Cu
2.0mm±10%	2/1.5oz		L4 L5	
2.0mm±10%	2/1.5oz			
2.0mm±10%	2/1.5oz			Core 0.6mm with 1.5/1.5 oz Cu

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
		10000	L2	
				Core 1.0mm with 1/1 oz Cu
			L3	
2.4mm±10%	1/1oz	4. 4. 4. 4. 4.		PP 0.11 mm dielectric constant 4.29
			L4	
				Core 1.0mm with 1/1 oz Cu
		00000	L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.11 mm dielectric constant 4.29
	2/1oz	11111	L2	
		11111		Core 1.0mm with 1/1 oz Cu
		11111	L3	
2.4mm±10%				PP 0.11 mm dielectric constant 4.29
			L4	
				Core 1.0mm with 1/1 oz Cu
			L5	
				PP 0.11 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.22 mm dielectric constant 4.29
		00000	L2	
		11111		Core 0.8mm with 1.5/1.5 oz Cu
		11111	L3	
2.4mm±10%	2/1.5oz	4444		PP 0.22 mm dielectric constant 4.29
			L4	
				Core 0.8mm with 1.5/1.5 oz Cu
			L5	
				PP 0.22 mm dielectric constant 4.29
			L6	Copper 50um(±5)um-plating to 70um

Note: The above is the standard stackup of PCBGOGO's 6-layer PCB board, we may change the layer stackup according to latest material or technology. For more details The custom stackup is available, feel free to contact us via service@pcbgogo.com.

8-Layer PCB Board	I			
Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
	Соррания (салания)	,	L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.2mm with 1/1 oz Cu
			L3	
				PP 0.11 mm dielectric constant 4.29
			L4	The state of the s
1.0mm±0.1mm	1/1oz	00000		Core 0.2mm with 1/1 oz Cu
			L5	
		3		PP 0.11 mm dielectric constant 4.29
		00000	L6	The state of the s
			20	Core 0.2mm with 1/1 oz Cu
		11111	L7	3010 0.211111 With 171 02 3u
			Li	PP 0.11 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
Thickness	Copper thick (outer/inner)	StackUp		
THICKHESS	Copper trick (outer/initer)	Зіаскор	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
		4	10	PP 0.11 mm dielectric constant 4.29
			L2	
			1.0	Core 0.2mm with 1/1 oz Cu
		00000	L3	
		0000		PP 0.11 mm dielectric constant 4.29
		4444	L4	
1.2mm±10%	1/1oz			Core 0.2mm with 1/1 oz Cu
			L5	
		00000		PP 0.11 mm dielectric constant 4.29
		11111	L6	
		4444		Core 0.2mm with 1/1 oz Cu
			L7	
				PP 0.11 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		Z		PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.2mm with 1/1 oz Cu
		00000	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	
1.2mm±10%	2/1oz			Core 0.2mm with 1/1 oz Cu
		00000	L5	
		00000		PP 0.11 mm dielectric constant 4.29
			L6	
				Core 0.2mm with 1/1 oz Cu
		00000	L7	
		7		PP 0.11 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um
	l	l		P. P

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
	,		L1	Copper 18 umplating to 35um
				PP 0.18 mm dielectric constant 4.29
			L2	
				Core 0.2mm with 1/1 oz Cu
			L3	
				PP 0.18 mm dielectric constant 4.29
			L4	
1.6mm±10%	1/1oz	00000		Core 0.2mm with 1/1 oz Cu
			L5	
				PP 0.18 mm dielectric constant 4.29
			L6	
				Core 0.2mm with 1/1 oz Cu
		00000	L7	
				PP 0.18 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.18 mm dielectric constant 4.29
			L2	
		00000		Core 0.2mm with 1/1 oz Cu
		4444	L3	
		4		PP 0.18 mm dielectric constant 4.29
			L4	
1.6mm±10%	2/1oz			Core 0.2mm with 1/1 oz Cu
		0000	L5	
		0000		PP 0.18 mm dielectric constant 4.29
		11111	L6	
				Core 0.2mm with 1/1 oz Cu
		0000	L7	55.040
			1.0	PP 0.18 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um PP 0.22 mm dielectric constant 4.29
			L2	FF 0.22 Hilli dielectric constant 4.29
		4	LZ	Core 0.2mm with 1.5/1.5 oz Cu
			L3	GOIG O.ZIIIIII WIUT 1.3/1.5 UZ GU
		00000	LU	PP 0.22 mm dielectric constant 4.29
		0000	L4	1 1 0.22 mm diciectife constant 4.29
1.6mm±10%	2/1.5oz	4444	LT	Core 0.2mm with 1.5/1.5 oz Cu
1.5111112 10 /0	2,1.502		L5	00/0 0.2/mm mat 1.0/1.0 02 0u
				PP 0.22 mm dielectric constant 4.29
			L6	
		00000		Core 0.2mm with 1.5/1.5 oz Cu
		11111	L7	
				PP 0.22 mm dielectric constant 4.29
l J			L8	Copper 50um(±5)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.18 mm dielectric constant 4.29
			L2	
		0000		Core 0.4mm with 1/1 oz Cu
		4444	L3	
				PP 0.18 mm dielectric constant 4.29
			L4	
2.0mm±10%	1/1oz	00000		Core 0.4mm with 1/1 oz Cu
		11111	L5	
		11111		PP 0.18 mm dielectric constant 4.29
			L6	
				Core 0.4mm with 1/1 oz Cu
		00000	L7	
		7		PP 0.18 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.18 mm dielectric constant 4.29
			L2	
		11111		Core 0.4mm with 1/1 oz Cu
			L3	
		3		PP 0.18 mm dielectric constant 4.29
			L4	
2.0mm±10%	2/1oz			Core 0.4mm with 1/1 oz Cu
		00000	L5	
		0000		PP 0.18 mm dielectric constant 4.29
		11111	L6	
				Core 0.4mm with 1/1 oz Cu
		00000	L7	
				PP 0.18 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um
			L1	Copper 50um(±5)um-plating to 70um
				PP 0.19 mm dielectric constant 4.29
			L2	
				Core 0.4mm with 1.5/1.5 oz Cu
		00000	L3	
		0000		PP 0.19 mm dielectric constant 4.29
			L4	
2.0mm±10%	2/1.5oz			Core 0.4mm with 1.5/1.5 oz Cu
			L5	
		00000		PP 0.19 mm dielectric constant 4.29
			L6	
				Core 0.4mm with 1.5/1.5 oz Cu
			L7	
				PP 0.19 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um

Thickness	Copper thick (outer/inner)	StackUp	Layer No.	Laminated chart Thickness
			L1	Copper 18 umplating to 35um
				PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.6mm with 1/1 oz Cu
		11111	L3	
				PP 0.11 mm dielectric constant 4.29
			L4	
2.4mm±10%	1/1oz			Core 0.6mm with 1/1 oz Cu
			L5	
		0000		PP 0.11 mm dielectric constant 4.29
		11111	L6	
		and and		Core 0.6mm with 1/1 oz Cu
			L7	
				PP 0.11 mm dielectric constant 4.29
			L8	Copper 18 umplating to 35um
			L1	Copper 50um(±5)um-plating to 70um
		4		PP 0.11 mm dielectric constant 4.29
			L2	
				Core 0.4mm with 1/1 oz Cu
		00000	L3	
		11111		PP 0.11 mm dielectric constant 4.29
		11111	L4	
2.4mm±10%	2/1oz			Core 0.6mm with 1/1 oz Cu
			L5	
		00000		PP 0.11 mm dielectric constant 4.29
		00000	L6	0 0.0
		0000	L7	Core 0.6mm with 1/1 oz Cu
			L/	DD 0.44 mm dialoctric constant 4.20
			L8	PP 0.11 mm dielectric constant 4.29
			L0 L1	Copper 50um(±5)um-plating to 70um Copper 50um(±5)um-plating to 70um
			LI	PP 0.29 mm dielectric constant 4.29
			L2	11 0.25 mm delectric constant 4.25
				Core 0.4mm with 1.5/1.5 oz Cu
		4444	L3	000 0 1.0/1.0 02 00
				PP 0.29 mm dielectric constant 4.29
			L4	11 0.20 mm dolodno constant 1.20
2.4mm±10%	2/1.5oz	00000	_,	Core 0.4mm with 1.5/1.5 oz Cu
		10000	L5	22.2 2 10. 110 02 00
		111111		PP 0.29 mm dielectric constant 4.29
			L6	
				Core 0.4mm with 1.5/1.5 oz Cu
		00000	L7	
				PP 0.29 mm dielectric constant 4.29
			L8	Copper 50um(±5)um-plating to 70um
	l .			11 ()

Note: The above is the standard stackup of PCBGOGO's 8-layer PCB board,we may change the layer stackup according to latest material or technology.For more detailsThe custom stackup is available, feel free to contact us via service@pcbgogo.com.